

CLAIMS

1 ^{sub 2} 1. A grid array signal conducting arrangement comprising at least one differential grid array
2 conductor pair and at least one non-differential grid array conductor pair, the at least one differential
3 grid array conductor pair having portions thereof which are more closely spaced in comparison to a
4 spacing of corresponding components in the at least one non-differential grid array conductor pair.

1 2. A grid array signal conducting arrangement as claimed in claim 1, where the grid array
2 signal conducting arrangement is provided in a grid array connector provided on at least one of a
3 receiving substrate and a semiconductor package.

1 3. A grid array signal conducting arrangement as claimed in claim 1, where the grid array
2 signal conducting arrangement conducts at least one differential pair signal.

1 4. A grid array signal conducting arrangement as claimed in claim 3, where the grid array
2 signal conducting arrangement provides at least one of greater coupling and greater common noise
3 between the differential grid array conductor pair than the non-differential grid array conductor pair.

1 5. A grid array signal conducting arrangement comprising:
2 at least one differential grid array conductor pair and at least one non-differential grid array
3 conductor pair; and
4 means for providing noise rejection capability in the grid array signal conducting
5 arrangement.

1 6. A grid array signal conducting arrangement as claimed in claim 5, where the grid array
2 signal conducting arrangement is provided in a grid array connector provided on at least one of a
3 receiving substrate and a semiconductor package.

1 7. A grid array signal conducting arrangement as claimed in claim 5, where the grid array
2 signal conducting arrangement conducts at least one differential pair signal.

1 8. A grid array signal conducting arrangement as claimed in claim 7, where the grid array
2 signal conducting arrangement provides at least one of greater coupling and greater common noise
3 between the differential grid array conductor pair than the non-differential grid array conductor pair

1 9. An electrical component comprising:
2 at least one of a receiving substrate and a semiconductor package; and
3 a grid array signal conducting arrangement comprising at least one differential grid array
4 conductor pair and at least one non-differential grid array conductor pair, the at least one differential
5 grid array conductor pair having portions thereof which are more closely spaced in comparison to a
6 spacing of corresponding components in the at least one non-differential grid array conductor pair.

1 10. An electrical component as claimed in claim 9, where the grid array signal conducting
2 arrangement conducts at least one differential pair signal.

1 11. An electrical component as claimed in claim 10, where the grid array signal conducting
2 arrangement provides at least one of greater coupling and greater common noise between the

3 differential grid array conductor pair than the non-differential grid array conductor pair.

1 12. A mounted electrical component arrangement comprising:

2 a plurality of electrical components; and

3 a grid array signal conducting arrangement comprising at least one differential grid array

4 conductor pair and at least one non-differential grid array conductor pair, the at least one differential

5 grid array conductor pair having portions thereof which are more closely spaced in comparison to a

6 spacing of corresponding components in the at least one non-differential grid array conductor pair.

1 13. A mounted electrical component arrangement as claimed in claim 12, where the grid array

2 signal conducting arrangement is provided in a grid array connector provided on at least one of a

3 receiving substrate and a semiconductor package.

1 14. A mounted electrical component arrangement as claimed in claim 12, where the grid array

2 signal conducting arrangement conducts at least one differential pair signal.

1 15. A mounted electrical component arrangement as claimed in claim 14, where the grid array

2 signal conducting arrangement provides at least one of greater coupling and greater common noise

3 between the differential grid array conductor pair than the non-differential grid array conductor pa

1 16. A method of increasing noise rejection capability of a grid array signal conducting

2 arrangement comprising:

3 orientating electrical conductive parts in the grid array signal conducting arrangement that

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- 4 conduct differential signals so as coupling distance between at least one pair of differential signals
5 is less than coupling distance between at least one pair of non-differential signals; and
6 conducting at least one pair of differential signals through the electrical conductive parts.

- 1 17. A method as claimed in claim 16, where the grid array signal conducting arrangement is
2 provided in a grid array connector provided on at least one of a receiving substrate and a
3 semiconductor package.

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